



Title of Change:	Final PCN for wire change from gold to copper, mold compound change and part number change.						
Proposed first ship date:	10 July 2015						
Contact information:	Contact your local ON Semiconductor Sales Office or < Yasuhiro Igarashi @onsemi.com >						
Samples:	Contact your local ON Semiconductor Sales Office						
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Kazutoshi.Kitazume@onsemi.com >.						
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <PCN.Support@onsemi.com>.						
Change Part Identification:	Affected products will be identified with new part number (changing suffix to "-W").						
	<table border="1"> <thead> <tr> <th>PART_ID</th> <th>New Part_ID</th> </tr> </thead> <tbody> <tr> <td>CPH6442-TL-E</td> <td>CPH6442-TL-W</td> </tr> </tbody> </table>			PART_ID	New Part_ID	CPH6442-TL-E	CPH6442-TL-W
PART_ID	New Part_ID						
CPH6442-TL-E	CPH6442-TL-W						
Change category(s):	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Product specific change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____						
Sites Affected:	<u>Site 1</u>	<u>Site 2</u>					
<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s):	ON Shenzhen, China						
Description and Purpose:							
This is a Final Process Change Notification to announce for below contents.							
1) Changing wire material from gold to copper 2) Changing part number from CPH6442-TL-E to CPH6442-TL-W. 3) Changing mold compound from halide to halide free.							
Reliability Data Summary:							
Test	Conditions	Results					
Steady State Operating Life	Tj=150degC	1000 hrs	Pass				
High Temperature Reverse Bias	Ta=150degC,VR=max	1000 hrs	Pass				
Temp Humidity Storage	Ta=85degC, RH=85%	1000 hrs	Pass				
Temperature Cycle	Ta=-55degC to 150degC 30min each	100 cycles	Pass				
Pressure Cooker	Ta=121degC,2.03x10 ⁵ Pa,100%	50 hrs	Pass				
High Temperature Storage	Ta=150degC	1000 hrs	Pass				
Resistance to Soldering heat(Reflow)	Solder Temp.:260degC±5degC	10s	Pass				
Solderability	Solder Temp.: 245degC±5degC	5 s	Pass				
Electrical Characteristic Summary:							
Electrical characteristics are not impacted.							
List of Affected Standard Parts:							
CPH6442-TL-E							